

**Amendments to the Abstract:**

Please replace the Abstract with the following:

[[The present invention discloses a]] A cooling structure for electronic devices  
[[which is characterized in that]] includes a plurality of electronic device accommodating  
boxes, in which electronic devices are accommodated, [[are accommodated]] disposed in a  
casing in multiple stages. [[, a]] A vent portion which allows ventilation between the inside  
and the outside of the casing is formed in a ceiling of the casing. [[, in]] In a first  
accommodating portion for accommodating the first electronic device accommodating box  
which is defined at the stage close to the ceiling, a hollow duct having two opening faces is  
arranged. [[, the]] The first opening face faces the vent portion and the second opening face  
faces a second accommodating portion for accommodating the second electronic device  
accommodating box which is defined at the stage remote from the ceiling. [[, air]] Air inside  
the second electronic device accommodating box ~~which is accommodated in the second~~  
~~accommodating portion~~ is discharged ~~outside the casing from the vent portion~~ through the  
inside of the duct. [[, and air]] Air inside of the first electronic device accommodating box  
~~which is accommodated in the first accommodating portion~~ is discharged ~~to the outside of the~~  
~~casing from the vent portion along an outer wall surface of the duct.~~